

PCN# : P2A5A
Issue Date : Nov. 20, 2012

DESIGN/PROCESS CHANGE NOTIFICATION

This is to inform you that a change is being made to the products listed below.

Unless otherwise indicated in the details of this notification, the identified change will have no impact on product quality, reliability, electrical, visual or mechanical performance and affected products will remain fully compliant to all published specifications. Products incorporating this change may be shipped interchangeably with existing unchanged products.

This change is planned to take effect in 90 calendar days from the date of this notification. Please work with your local Fairchild Sales Representative to manage your inventory of unchanged product if your evaluation of this change will require more than 90 calendar days.

Please contact your local Customer Quality Engineer within 30 days of receipt of this notification if you require any additional data or samples. Alternatively, you may send an email request for data, samples or other information to PCNSupport@fairchildsemi.com.

Implementation of change:

Expected First Shipment Date for Changed Product : Feb. 18, 2013

Expected First Date Code of Changed Product :1307

Description of Change (From) :

6 inch wafer diameter for the detector die component of all listed products as per below list.

Description of Change (To) :

8 inch wafer diameter for the detector die component of all listed products as per below list.

Reason for Change:

Fairchild Semiconductor is closing the 6" fabrication line and qualifying a 8" fabrication line. This is to increase the production capacity in our wafer fabrication facilities in USA.

Affected Product(s):

FOD410	FOD4108	FOD4108S
FOD4108SD	FOD4108SDV	FOD4108SV
FOD4108TV	FOD4108V	FOD410S
FOD410SD	FOD410SDV	FOD410SV
FOD410TV	FOD410V	FOD4116
FOD4116S	FOD4116SD	FOD4116SDV
FOD4116SV	FOD4116TV	FOD4116V
FOD4118	FOD4118S	FOD4118SD
FOD4118SDV	FOD4118SV	FOD4118TV
FOD4118V	FOD420	FOD4208
FOD4208S	FOD4208SD	FOD4208SDV
FOD4208SV	FOD4208TV	FOD4208V
FOD420S	FOD420SD	FOD420SDV
FOD420SV	FOD420TV	FOD420V
FOD4216	FOD4216S	FOD4216SD
FOD4216SDV	FOD4216SV	FOD4216TV
FOD4216V	FOD4218	FOD4218S
FOD4218SD	FOD4218SDV	FOD4218SV
FOD4218TV	FOD4218V	

Qualification Plan	Device	Package	Process	No. of Lots
Q20100506	FOD4218	6PB	N/A	3

Test Description:	Condition:	Standard :	Duration:	Results:
MSL1 Precondition	260C, 3 cycles	JESD22-A113		0/924
Bond Pull		JESD22-C100		0/33
Bond Shear		AEC-Q100-001		0/33
Die Shear		MIL-STD-883-2019		0/33
High Temperature Op Life Test	100C	JESD22-A108	168 hrs	0/231
High Temperature Storage Life	125C	JESD22-A103	168 hrs	0/231
Temperature Cycle	-40C, 125C	JESD22-A104	200 cycles	0/231
High Temperature Reverse Bias	85 C	JESD22-A108	168 hrs	0/231